

DXM-EXY



Equipment Performance

1. Realize automatic orientation and operation to avoid manual operation errors.
2. Automatically measure the crystal angle and automatically adjust the transmitting and receiving angles.
3. Calculate the rotation angle and swing angle values after measurement, and automatically adjust according to the angle.
4. The tools has a memory function, there is no need to calibrate it every time it is turned on.
5. Multiple crystals can be bonded to one material plate.
6. The X and Y axes of the bonded ingot can be double-checked to ensure the accuracy of the crystal orientation before cutting.
7. The three functions of measurement, angle swing and material sticking can be realized on the same working platform.
8. Selective touch screen operation simplifies input conditions and reduces misoperation rates.
9. The equipment is a fully enclosed body and the shutter automatically closes to improve personal safety.
10. The X-ray system automatically positions according to the crystal ingot clamping position.
11. The bonding pressure can be set and monitored in real time.
12. Error operation alarm reminder function.
13. The tools has data output function.
14. The crystal ingot clamping force can be adjusted.

Item	Specifications
Crystal Diameter	Ingot 6、8 inches Or ingot 4、6 inches
Crystal length	SiC: 5~60mm; Other Crystal: 60~300mm
Crystal weight	Single ingot weight less than 30KG
Measurement angle	+12°~48°
Bonding accuracy	Within $\pm 0.05^\circ$ (99% above)
Bonding angle adjustment range	Y-axis deviation $\pm 1^\circ$; X-axis deviation $\pm 4^\circ$.

